

# MDHT3N40

## N-Channel MOSFET 400V, 1.5A, 3.4Ω

MDHT3N40 N-channel MOSFET 400V

### General Description

The MDHT3N40 uses advanced Magnachip's MOSFET Technology, which provides low on-state resistance, high switching performance and excellent quality.

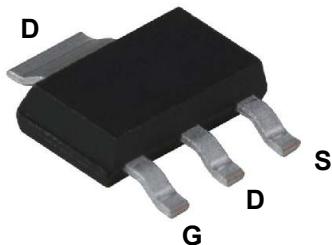
MDHT3N40 is suitable device for SMPS, HID and general purpose applications.

### Features

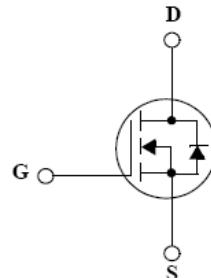
- $V_{DS} = 400V$
- $I_D = 1.5A$
- $R_{DS(ON)} \leq 3.4\Omega$
- $@V_{GS} = 10V$
- $@V_{GS} = 10V$

### Applications

- Power Supply
- PFC
- LED TV



SOT-223



### Absolute Maximum Ratings ( $T_a = 25^\circ C$ )

Characteristics	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	400	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Continuous Drain Current	$I_D$	1.5	A
$T_c=25^\circ C$		0.9	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	6.0	A
Power Dissipation	$P_D$	2.1	W
$T_c=25^\circ C$		0.017	$W/^\circ C$
Peak Diode Recovery $dV/dt^{(3)}$	$dV/dt$	4.5	V/ns
Repetitive Pulse Avalanche Energy <sup>(1)</sup>	$E_{AR}$	0.21	mJ
Avalanche current <sup>(1)</sup>	$I_{AR}$	1.5	A
Single Pulse Avalanche Energy <sup>(4)</sup>	$E_{AS}$	45	mJ
Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~150	°C

### Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Ambient <sup>(1)</sup>	$R_{\theta JA}$	60	°C/W

## Ordering Information

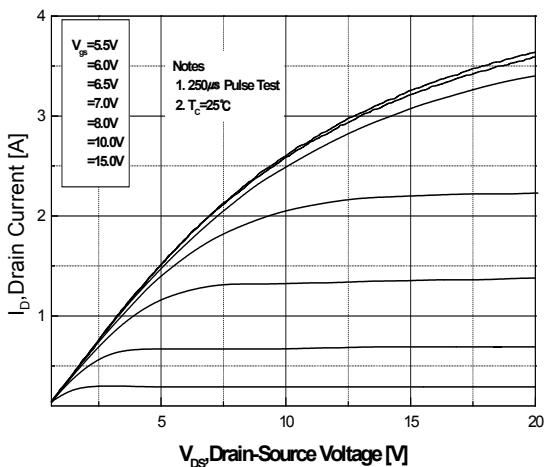
Part Number	Temp. Range	Package	Packing	RoHS Status
MDHT3N40URH	-55~150°C	SOT-223	Reel and Tape	Halogen Free

## Electrical Characteristics (Ta =25°C)

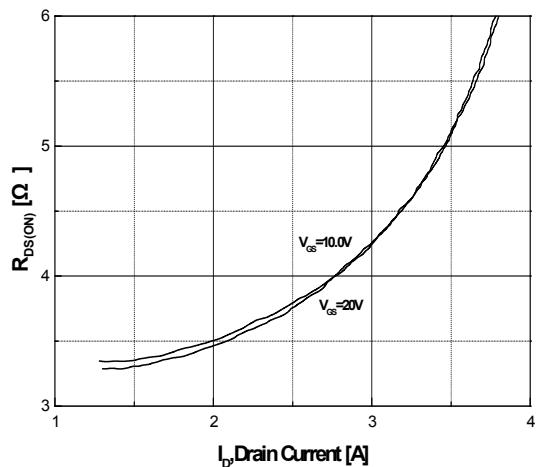
Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	400	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	3.0	-	5.0	
Drain Cut-Off Current	I <sub>DSS</sub>	V <sub>DS</sub> = 400V, V <sub>GS</sub> = 0V	-	-	1	μA
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V	-	-	100	nA
Drain-Source ON Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.75A		2.8	3.4	Ω
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> = 30V, I <sub>D</sub> = 0.75A	-	2.0	-	S
<b>Dynamic Characteristics</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 320V, I <sub>D</sub> = 3.0A, V <sub>GS</sub> = 10V	-	5.1	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	1.4	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	3.9	-	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1.0MHz	-	167	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	2	-	
Output Capacitance	C <sub>oss</sub>		-	27	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 200V, I <sub>D</sub> = 3.0A, R <sub>G</sub> = 25Ω	-	10	-	ns
Rise Time	t <sub>r</sub>		-	30	-	
Turn-Off Delay Time	t <sub>d(off)</sub>		-	12	-	
Fall Time	t <sub>f</sub>		-	25	-	
<b>Drain-Source Body Diode Characteristics</b>						
Maximum Continuous Drain to Source Diode Forward Current	I <sub>S</sub>				1.5	A
Source-Drain Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1.5A, V <sub>GS</sub> = 0V	-		1.4	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 3.0A, di/dt = 100A/μs <sup>(3)</sup>	-	185	-	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	0.6	-	μC

Note :

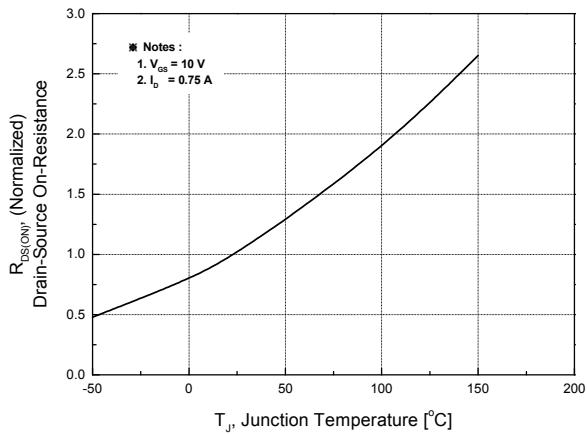
1. Pulse width is based on R<sub>gUC</sub> & R<sub>gJA</sub> and the maximum allowed junction temperature of 150°C.
2. Pulse test: pulse width ≤300us, duty cycle≤2%, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C.
3. I<sub>SD</sub> ≤3.0A, di/dt≤200A/us, V<sub>DD</sub>≤BV<sub>DSS</sub>, Starting T<sub>J</sub>=25°C
4. L=8.75mH, I<sub>AS</sub>=3.0A, V<sub>DD</sub>=50V, R<sub>g</sub> =25Ω, Starting T<sub>J</sub>=25°C



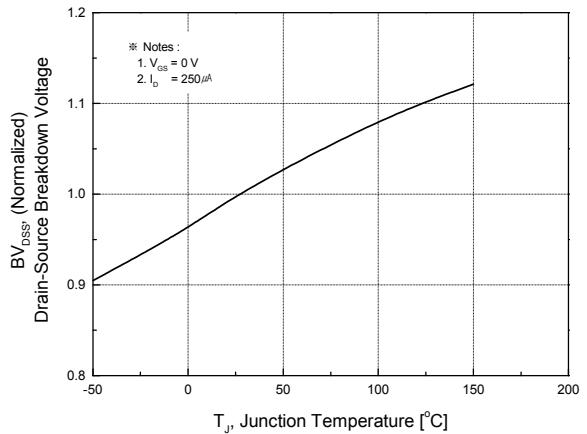
**Fig.1 On-Region Characteristics**



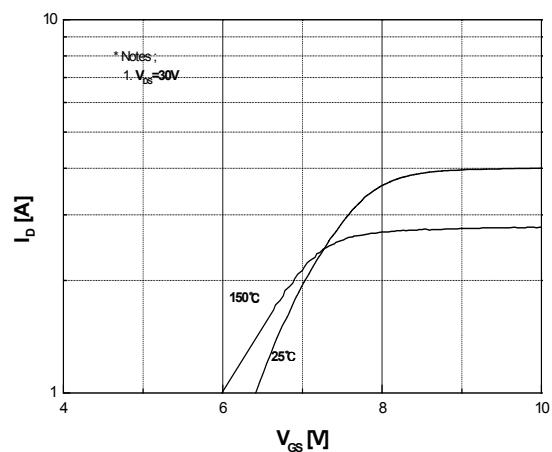
**Fig.2 On-Resistance Variation with Drain Current and Gate Voltage**



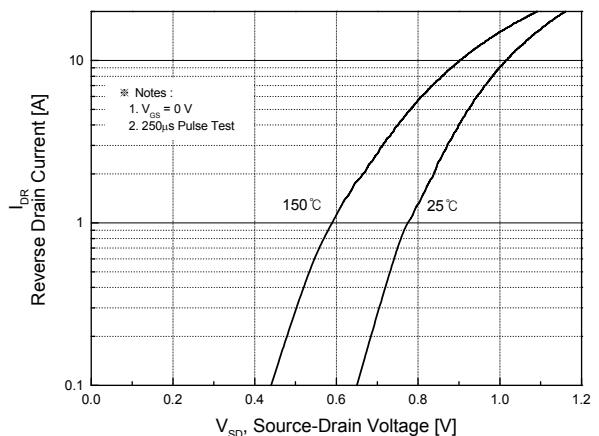
**Fig.3 On-Resistance Variation with Temperature**



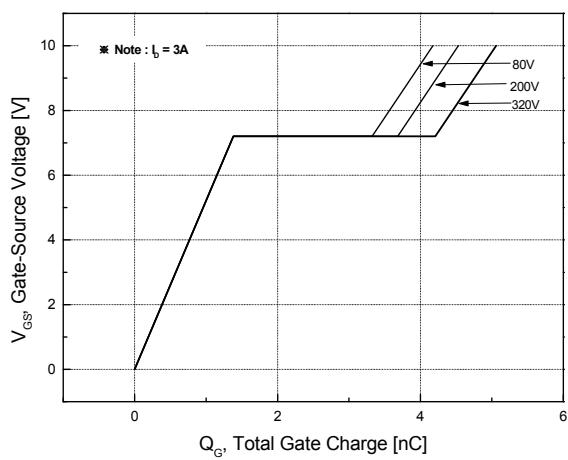
**Fig.4 Breakdown Voltage Variation vs. Temperature**



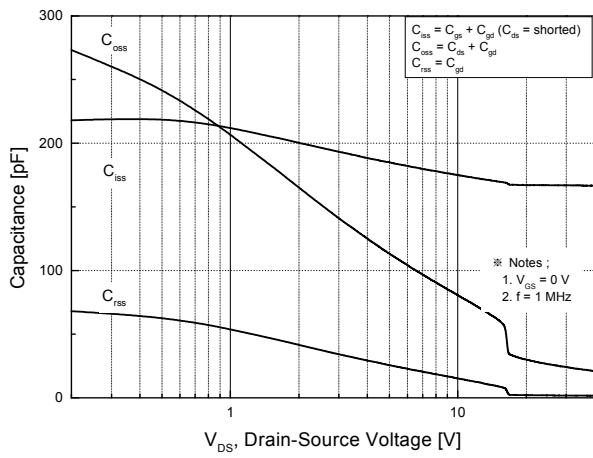
**Fig.5 Transfer Characteristics**



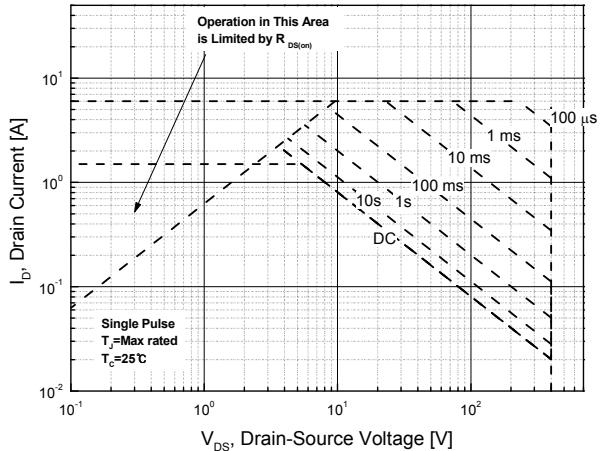
**Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature**



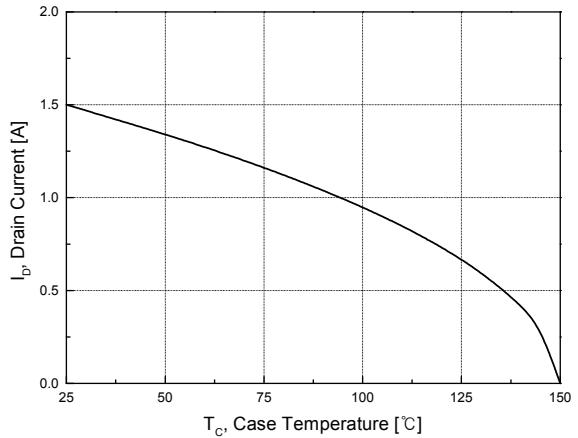
**Fig.7 Gate Charge Characteristics**



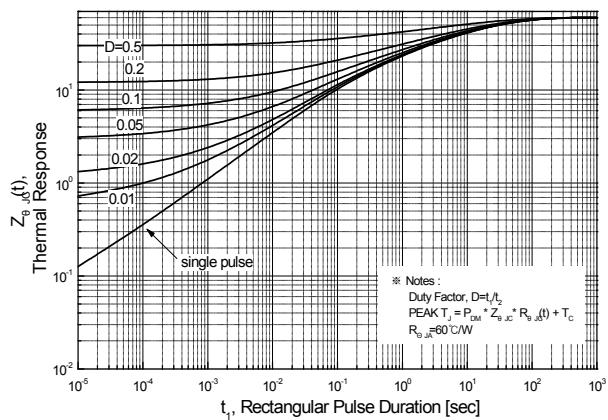
**Fig.8 Capacitance Characteristics**



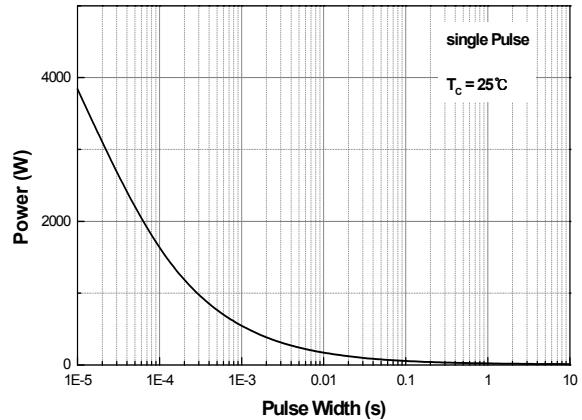
**Fig.9 Maximum Safe Operating Area**



**Fig.10 Maximum Drain Current vs. Case Temperature**



**Fig.11 Transient Thermal Response Curve**

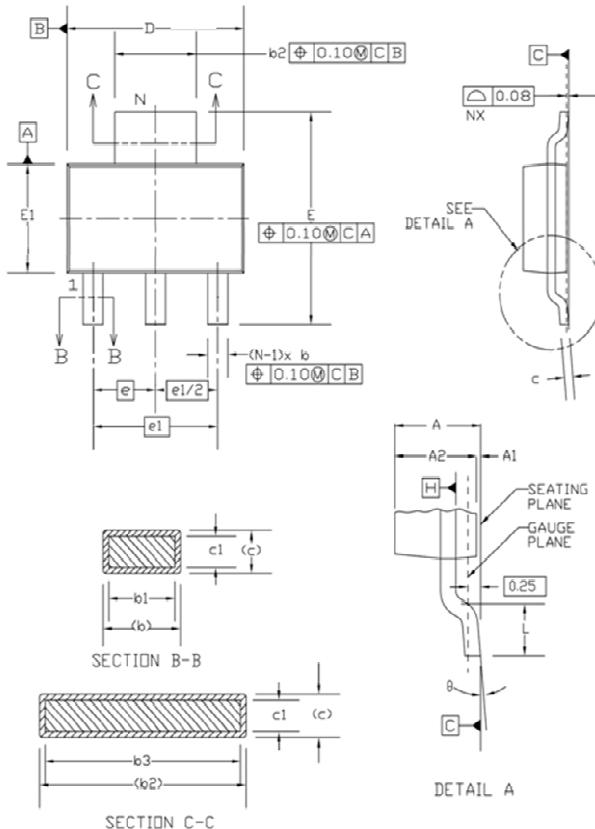


**Fig.12 Single Pulse Maximum Power Dissipation**

## Physical Dimension

### SOT-223

Dimensions are in millimeters, unless otherwise specified



Symbol	Min	Nom	Max
A	-	-	1.80
A1	0.00	-	0.10
A2	1.50	-	1.70
b	0.30	-	0.84
b1	0.60	-	0.79
b2	2.90	-	3.10
b3	2.84	-	3.05
c	0.23	-	0.35
c1	0.23	-	0.33
D	6.20	-	6.70
E	6.70	-	7.30
E1	3.30	-	3.70
e	2.30 BASIC		
e1	4.60 BASIC		
L	0.75	-	-
$\theta$	0°	-	10°

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